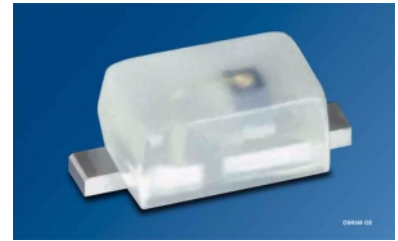


SmartLED™ Hyper-Bright LED

LS L896, LA L896, LO L896, LY L896



Besondere Merkmale

- **Gehäusotyp:** SMT Gehäuse SCD 80
- **Besonderheit des Bauteils:** kleinste Bauform 1,7 mm x 0,8 mm x 0,65 mm (LxBxH)
- **Wellenlänge:** 633 nm (super-rot), 615 nm (amber), 606 nm (orange), 587 nm (gelb)
- **Abstrahlwinkel:** extrem breite Abstrahlcharakteristik (160°)
- **Technologie:** InGaAlP
- **optischer Wirkungsgrad:** 7 lm/W (super-rot), 11 lm/W (gelb, orange, amber)
- **Gruppierungsparameter:** Lichtstärke, Wellenlänge
- **Verarbeitungsmethode:** für alle SMT-Bestücktechniken geeignet
- **Lötmethode:** IR Reflow Löten und Wellenlöten (TTW)
- **Vorbehandlung:** nach JEDEC Level 2
- **Gurtung:** 8 mm Gurt mit 10000/Rolle, ø180 mm oder 40000/Rolle, ø330 mm

Anwendungen

- Informationsanzeigen im Außenbereich
- Flache Hinterleuchtung (LCD, Mobile Phone, Schalter, Display)
- Signal- und Symbolleuchten
- Markierungsbeleuchtung (z.B. Stufen, Fluchtwege, u.ä.)

Features

- **package:** SMT package SCD 80
- **feature of the device:** smallest package 1.7 mm x 0.8 mm x 0.65 mm (LxWxH)
- **wavelength:** 633 nm (super-red), 615 nm (amber), 606 nm (orange), 587 nm (yellow)
- **viewing angle:** extremely wide (160°)
- **technology:** InGaAlP
- **optical efficiency:** 7 lm/W (super-red), 11 lm/W (yellow, orange, amber)
- **grouping parameter:** luminous intensity, wavelength
- **assembly methods:** suitable for all SMT assembly methods
- **soldering methods:** IR reflow soldering and TTW soldering
- **preconditioning:** acc. to JEDEC Level 2
- **taping:** 8 mm tape with 10000/reel, ø180 mm or 40000/reel, ø330 mm

Applications

- outdoor displays
- flat backlighting (LCD, cellular phones, switches, displays)
- signal and symbol luminaire
- marker lights (e.g. steps, exit ways, etc.)

Typ Type	Emissions- farbe Color of Emission	Gehäusefarbe Color of Package	Lichtstärke Luminous Intensity $I_F = 20 \text{ mA}$ $I_V \text{ (mcd)}$	Lichtstrom Luminous Flux $I_F = 20 \text{ mA}$ $\Phi_V \text{ (mlm)}$	Bestellnummer Ordering Code
LS L896-M1N1-1 LS L896-N1P2-1	super-red	colorless diffused	18.0 ... 35.5 28.0 ... 71.0	105 (typ.) 200 (typ.)	Q62703-Q6020 Q62703-Q6160
LA L896-P1Q1-1 LA L896-Q1R2-1	amber	colorless diffused	45.0 ... 90.0 71.0 ... 180.0	270 (typ.) 500 (typ.)	Q62703-Q6203 Q62703-Q6204
LO L896-P1Q1-24 LO L896-Q1R2-24	orange	colorless diffused	45.0 ... 90.0 71.0 ... 180.0	270 (typ.) 500 (typ.)	Q62703-Q6207 Q62703-Q6208
LY L896-P1Q1-26 LY L896-Q1R2-26	yellow	colorless diffused	45.0 ... 90.0 71.0 ... 180.0	270 (typ.) 500 (typ.)	Q62703-Q6021 Q62703-Q6164

Anm.: -1 gesamter Farbbereich (siehe **Seite 4**)

-24 gesamter Farbbereich, Lieferung in Einzelgruppen (siehe **Seite 5**)

-26 gesamter Farbbereich, Lieferung in Einzelgruppen (siehe **Seite 5**)

Die Standardlieferform von Serientypen beinhaltet eine untere bzw. eine obere Familiengruppe, die aus nur 3 bzw. 4 Halbgruppen besteht. Einzelne Halbgruppen sind nicht erhältlich.

In einer Verpackungseinheit / Gurt ist immer nur eine Halbgruppe enthalten.

Note: -1 Total color tolerance range (please see **page 4**)

-24 Total color tolerance range, delivery in single groups (please see **page 5**)

-26 Total color tolerance range, delivery in single groups (please see **page 5**)

The standard shipping format for serial types includes a lower or upper family group of 3 or 4 individual groups. Individual half groups are not available.

No packing unit / tape ever contains more than one luminous intensity half group.

Grenzwerte
Maximum Ratings

Bezeichnung Parameter	Symbol Symbol	Werte Values		Einheit Unit
		LS, LA	LO, LY	
Betriebstemperatur Operating temperature range	T_{op}	– 40 ... + 100		°C
Lagertemperatur Storage temperature range	T_{stg}	– 40 ... + 100		°C
Sperrschichttemperatur Junction temperature	T_j	+ 110		°C
Durchlassstrom Forward current	I_F	60	30	mA
Stoßstrom Surge current $t \leq 10 \mu s, D = 0.1$	I_{FM}	0.5	0.25	A
Sperrspannung Reverse voltage	V_R	3		V
Leistungsaufnahme Power consumption	P_{tot}	170	80	mW
Wärmewiderstand Thermal resistance Sperrschicht/Umgebung Junction/ambient	$R_{th JA}$	500		K/W
Sperrschicht/Löt看 Junction/solder point Montage auf PC-Board FR 4 (Padgröße $\geq 5 \text{ mm}^2$) mounted on PC board FR 4 (pad size $\geq 5 \text{ mm}^2$)	$R_{th JS}$	290		K/W

Kennwerte ($T_A = 25\text{ °C}$)

Characteristics

Bezeichnung Parameter	Symbol Symbol	Werte Values				Einheit Unit
		LS	LA	LO	LY	
Wellenlänge des emittierten Lichtes (typ.) Wavelength at peak emission $I_F = 20\text{ mA}$	λ_{peak}	645	622	610	591	nm
Dominantwellenlänge ¹⁾ (typ.) Dominant wavelength $I_F = 20\text{ mA}$	λ_{dom}	633 ± 6	615 ± 6	606 $+3/-6$	587 $+8/-7$	nm
Spektrale Bandbreite bei 50 % $I_{\text{rel max}}$ (typ.) Spectral bandwidth at 50 % $I_{\text{rel max}}$ $I_F = 20\text{ mA}$	$\Delta\lambda$	16	16	16	15	nm
Abstrahlwinkel bei 50 % I_V (Vollwinkel) (typ.) Viewing angle at 50 % I_V	2ϕ	160	160	160	160	Grad deg.
Durchlassspannung ²⁾ (typ.) Forward voltage $I_F = 20\text{ mA}$	V_F V_F	2.0 2.4	2.0 2.4	2.0 2.4	2.0 2.4	V V
Sperrstrom (typ.) Reverse current $V_R = 5\text{ V}$	I_R I_R	0.01 10	0.01 10	0.01 10	0.01 10	μA μA
Temperaturkoeffizient von λ_{peak} (typ.) Temperature coefficient of λ_{peak} $I_F = 20\text{ mA}; -10^\circ\text{C} \leq T \leq 100^\circ\text{C}$	$TC_{\lambda_{\text{peak}}}$	0.14	0.13	0.13	0.13	nm/K
Temperaturkoeffizient von λ_{dom} (typ.) Temperature coefficient of λ_{dom} $I_F = 20\text{ mA}; -10^\circ\text{C} \leq T \leq 100^\circ\text{C}$	$TC_{\lambda_{\text{dom}}}$	0.01	0.06	0.07	0.10	nm/K
Temperaturkoeffizient von V_F (typ.) Temperature coefficient of V_F $I_F = 20\text{ mA}; -10^\circ\text{C} \leq T \leq 100^\circ\text{C}$	TC_V	-2.0	-1.8	-1.7	-2.5	mV/K
Optischer Wirkungsgrad (typ.) Optical efficiency $I_F = 20\text{ mA}$	η_{opt}	7	11	11	11	lm/W

¹⁾ Wellenlängengruppen werden mit einer Stromeinprägedauer von 25 ms und einer Genauigkeit von $\pm 1\text{ nm}$ ermittelt.
Wavelength groups are tested at a current pulse duration of 25 ms and a tolerance of $\pm 1\text{ nm}$.

²⁾ Spannungswerte werden mit einer Stromeinprägedauer von 1 ms und einer Genauigkeit von $\pm 0,1\text{ V}$ ermittelt.
Voltages are tested at a current pulse duration of 1 ms and a tolerance of $\pm 0.1\text{ V}$.

1) Wellenlängengruppen / Wavelength groups

Gruppe Group	yellow		orange		Einheit Unit
	min.	max.	min.	max.	
2	580	583	600	603	nm
3	583	586	603	606	nm
4	586	589	606	609	nm
5	589	592			nm
6	592	595			nm

Helligkeits-Gruppierungsschema
Luminous Intensity Groups

Lichtgruppe Luminous Intensity Group	Lichtstärke Luminous Intensity I_V (mcd)	Lichtstrom Luminous Flux Φ_V (mlm)
M1	18.0 ... 22.4	80 (typ.)
M2	22.4 ... 28.0	100 (typ.)
N1	28.0 ... 35.5	125 (typ.)
N2	35.5 ... 45.0	160 (typ.)
P1	45.0 ... 56.0	200 (typ.)
P2	56.0 ... 71.0	250 (typ.)
Q1	71.0 ... 90.0	320 (typ.)
Q2	90.0 ... 112.0	400 (typ.)
R1	112.0 ... 140.0	500 (typ.)
R2	140.0 ... 180.0	640 (typ.)

Helligkeitswerte werden mit einer Stromeinprägungsdauer von 25 ms und einer Genauigkeit von $\pm 11\%$ ermittelt.
Luminous intensity is tested at a current pulse duration of 25 ms and a tolerance of $\pm 11\%$.

Gruppenbezeichnung auf Etikett
Group Name on Label

Beispiel: R2-3

Example: R2-3

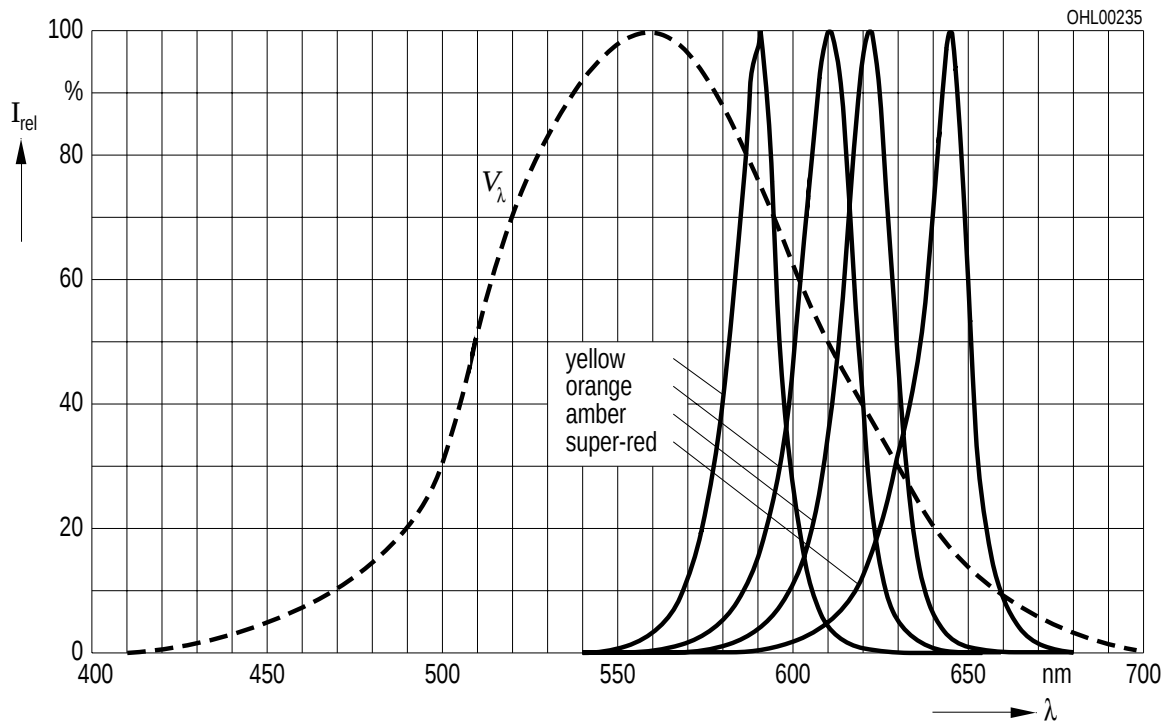
Lichtgruppe Luminous Intensity Group	Halbgruppe Half Group	Wellenlänge Wavelength
R	2	3

Relative spektrale Emission $I_{\text{rel}} = f(\lambda)$, $T_A = 25^\circ\text{C}$, $I_F = 20\text{ mA}$

Relative Spectral Emission

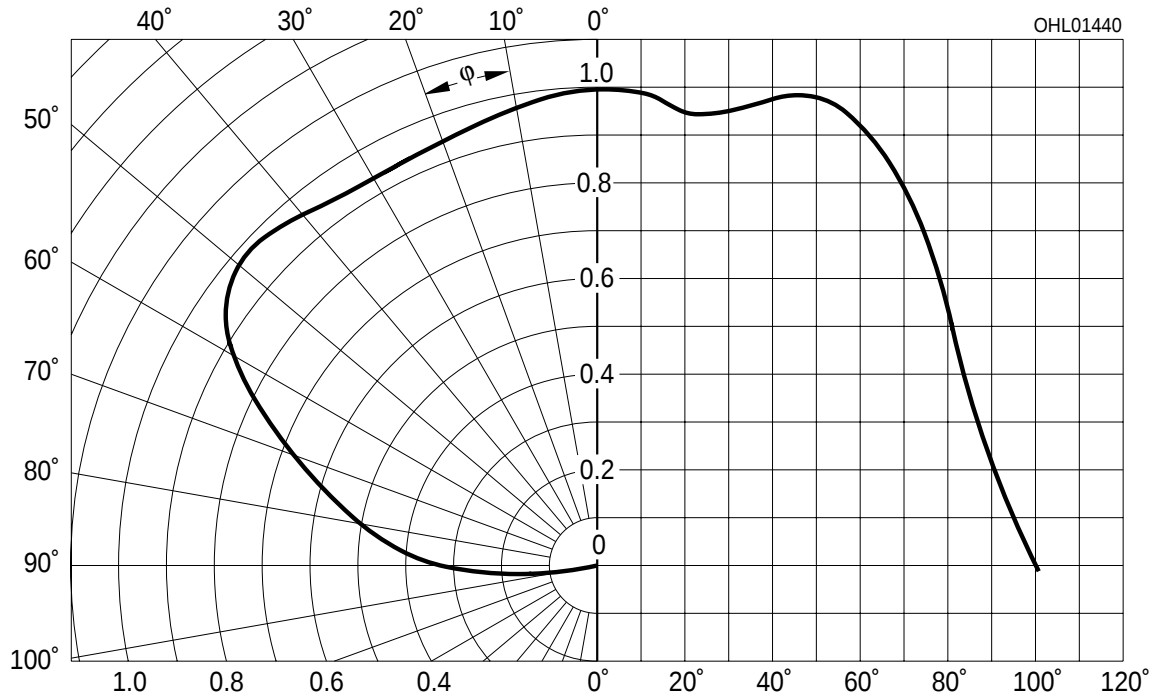
$V(\lambda)$ = spektrale Augenempfindlichkeit

Standard eye response curve



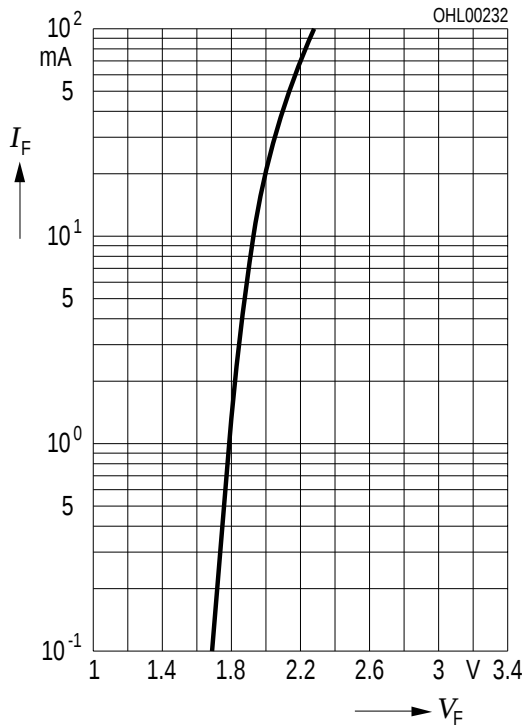
Abstrahlcharakteristik $I_{\text{rel}} = f(\varphi)$

Radiation Characteristic



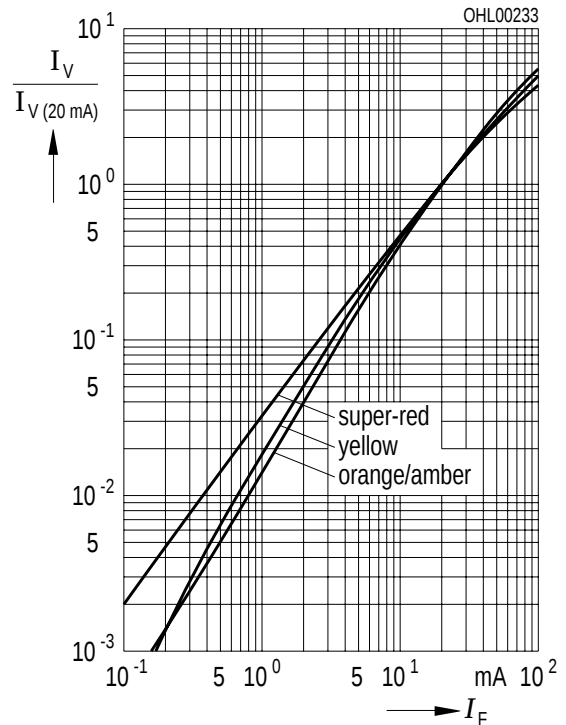
Durchlassstrom $I_F = f(V_F)$ Forward Current

$T_A = 25\text{ °C}$



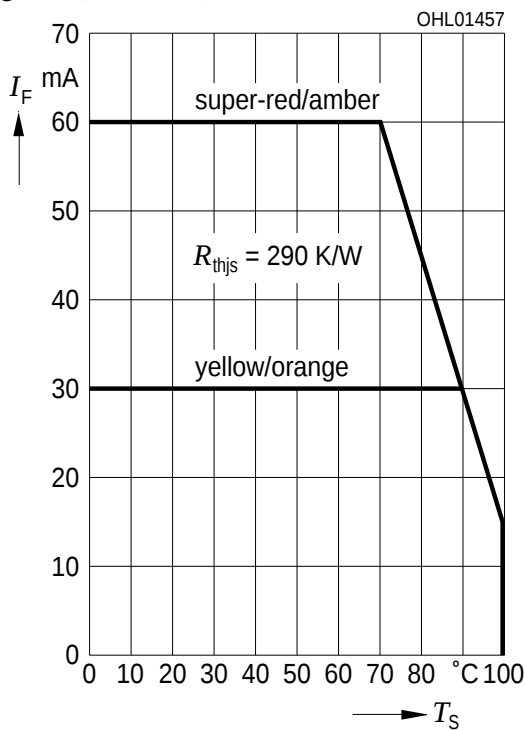
Relative Lichtstärke $I_V/I_{V(20\text{ mA})} = f(I_F)$ Relative Luminous Intensity

$T_A = 25\text{ °C}$



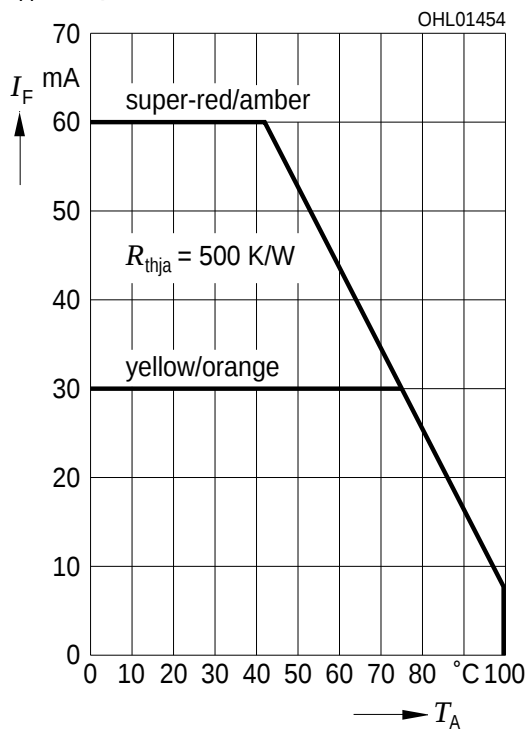
Maximal zulässiger Durchlassstrom $I_F = f(T)$ Max. Permissible Forward Current

T_S : temp. solder point



Maximal zulässiger Durchlassstrom $I_F = f(T)$ Max. Permissible Forward Current

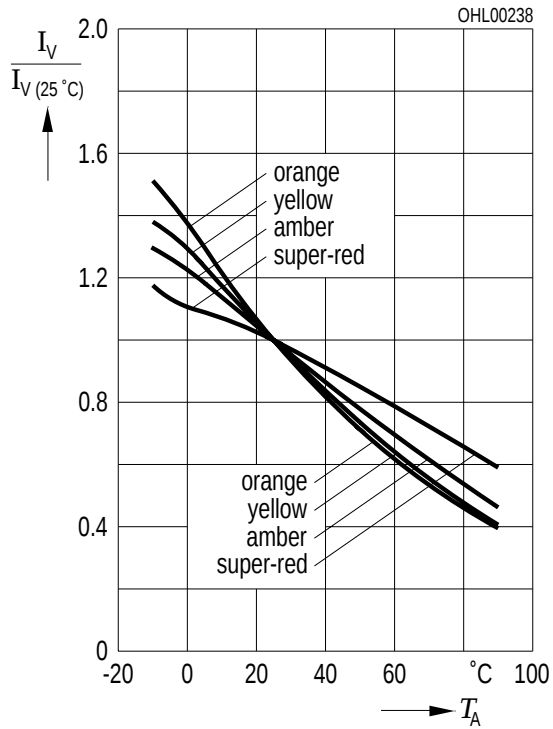
T_A : temp. ambient



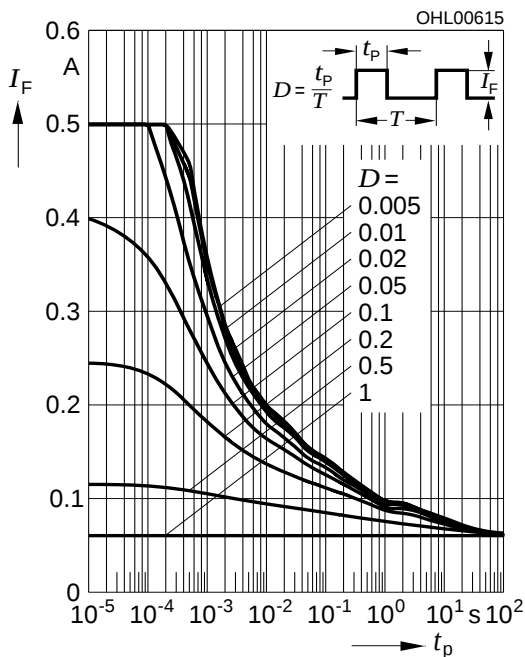
Relative Lichtstärke $I_V/I_{V(25^\circ\text{C})} = f(T_A)$

Relative Luminous Intensity

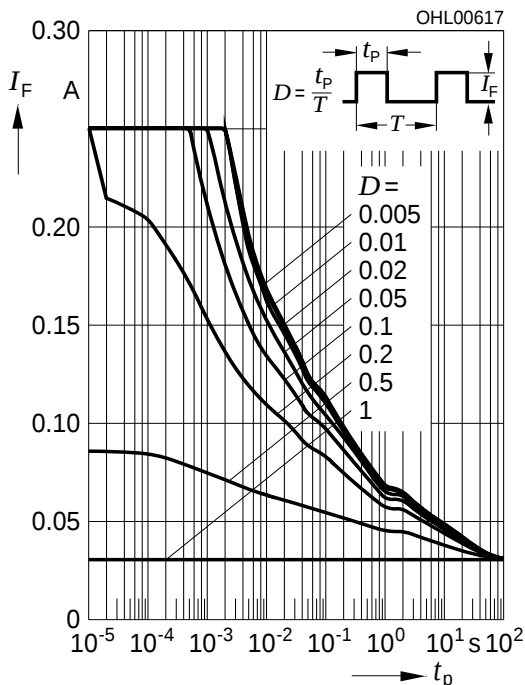
$I_F = 20 \text{ mA}$



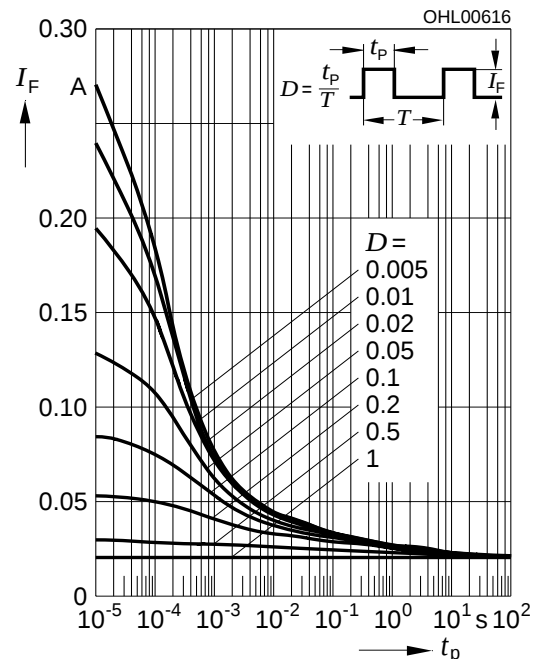
Zulässige Impulsbelastbarkeit $I_F = f(t_p)$
Permissible Pulse Handling Capability
Duty cycle $D = \text{parameter}$, $T_A = 25^\circ\text{C}$
LS, LA



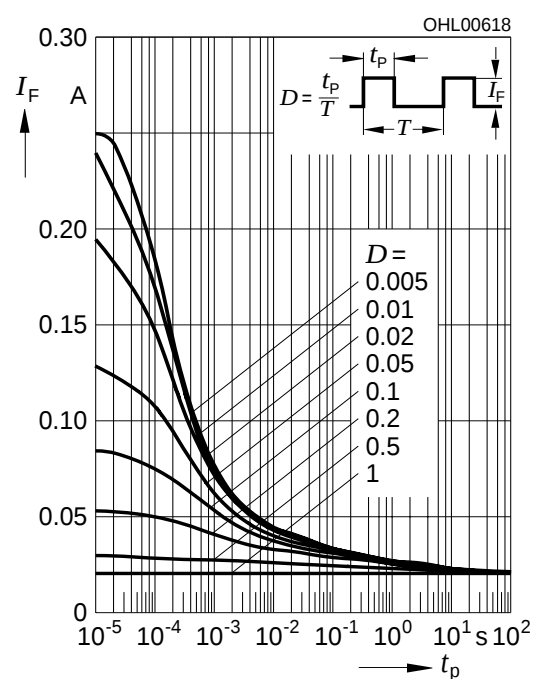
Zulässige Impulsbelastbarkeit $I_F = f(t_p)$
Permissible Pulse Handling Capability
Duty cycle $D = \text{parameter}$, $T_A = 25^\circ\text{C}$
LO, LY



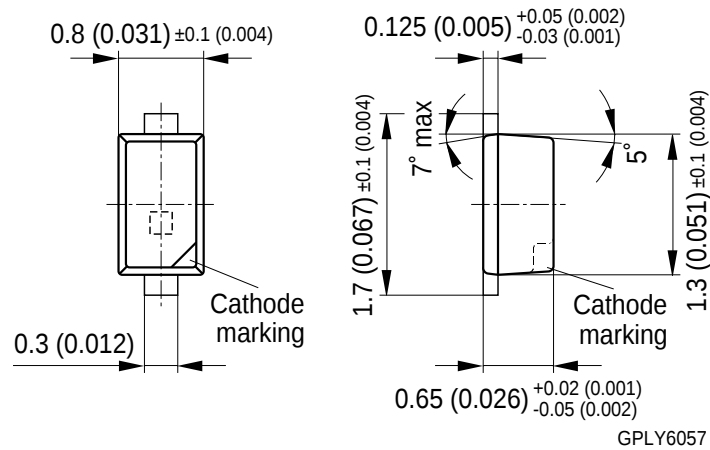
Zulässige Impulsbelastbarkeit $I_F = f(t_p)$
Permissible Pulse Handling Capability
Duty cycle $D = \text{parameter}$, $T_A = 85^\circ\text{C}$
LS, LA



Zulässige Impulsbelastbarkeit $I_F = f(t_p)$
Permissible Pulse Handling Capability
Duty cycle $D = \text{parameter}$, $T_A = 85^\circ\text{C}$
LO, LY



**Maßzeichnung
Package Outlines**

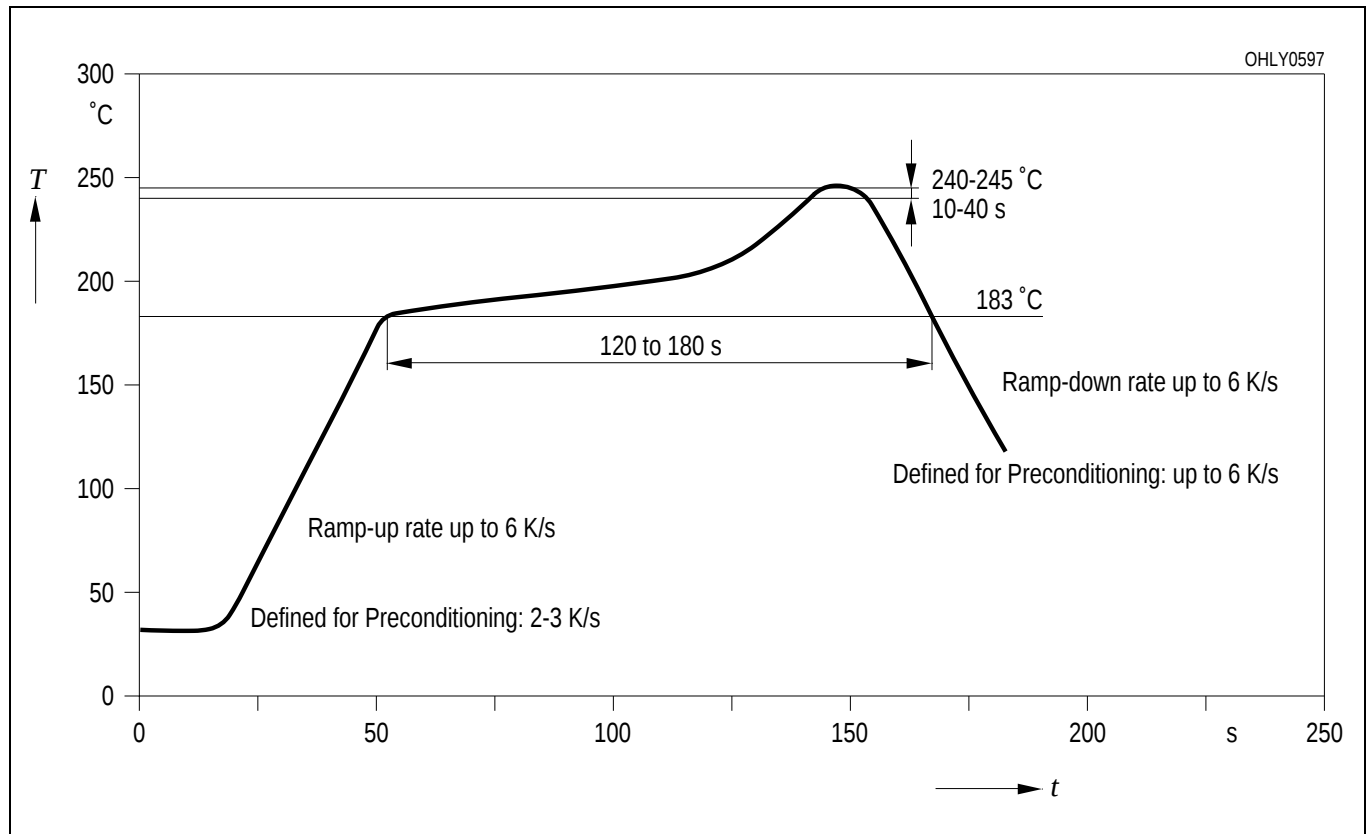


Maße werden wie folgt angegeben: mm (inch) / Dimensions are specified as follows: mm (inch).

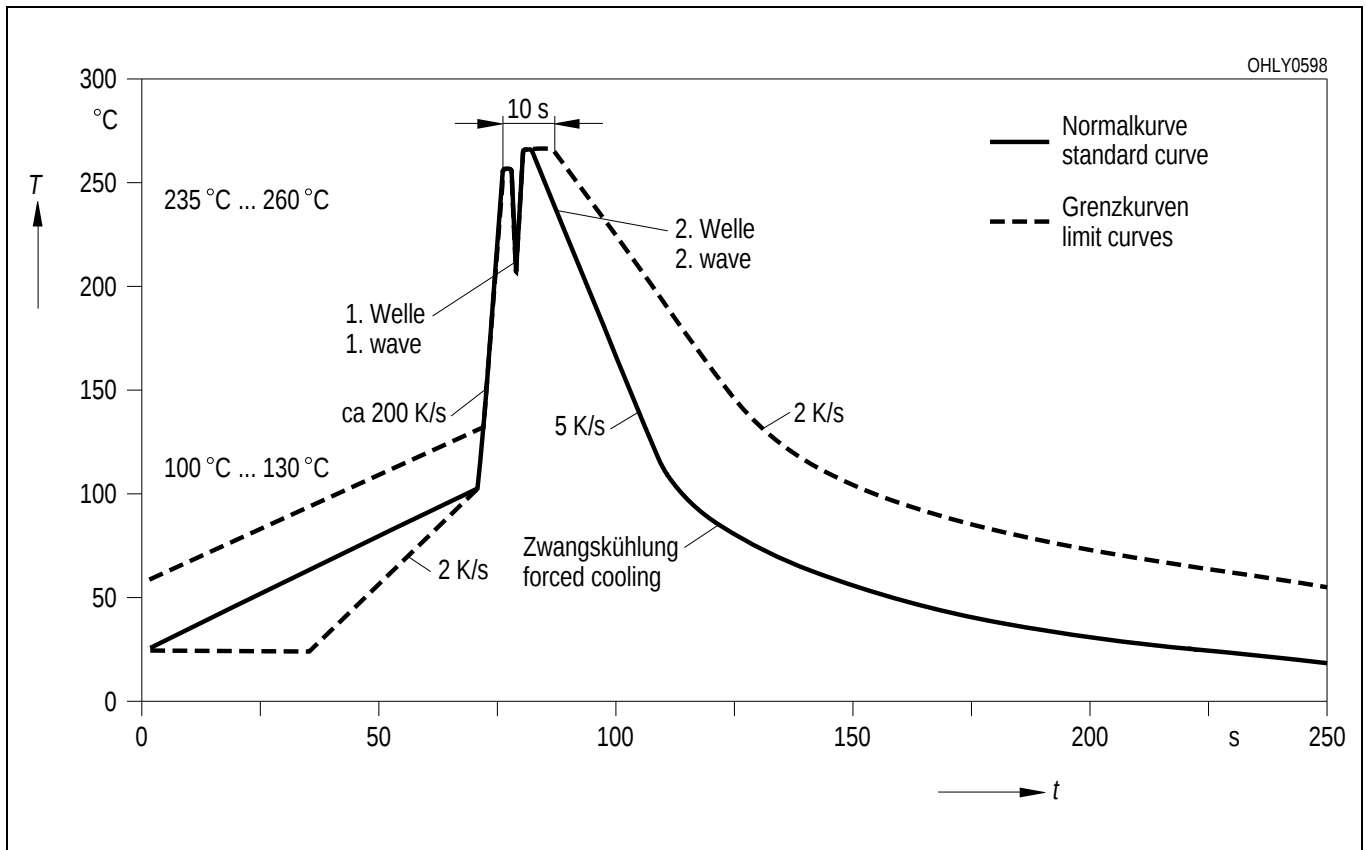
Gewicht / Approx. weight: 1,4 mg

Lötbedingungen Vorbehandlung nach JEDEC Level 2
Soldering Conditions Preconditioning acc. to JEDEC Level 2

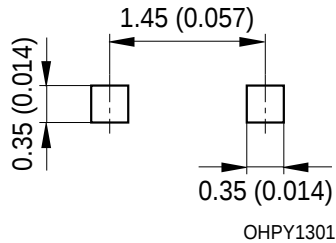
IR-Reflow Lötprofil (nach IPC 9501)
IR Reflow Soldering Profile (acc. to IPC 9501)



Wellenlöten (TTW) (nach CECC 00802)
TTW Soldering (acc. to CECC 00802)

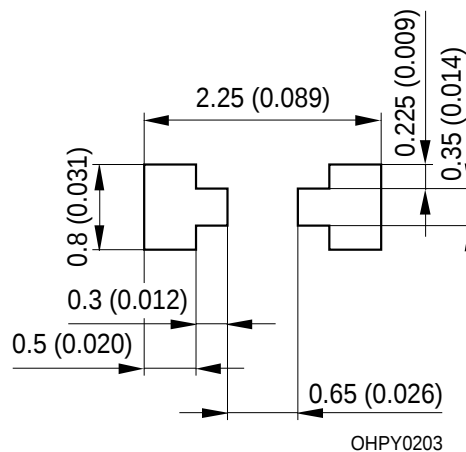


Empfohlenes Lötpaddesign IR Reflow Lötten
Recommended Solder Pad IR Reflow Soldering



Maße werden wie folgt angegeben: mm (inch) / Dimensions are specified as follows: mm (inch).
 Gehäuse für Wellenlöten (TTW) geeignet / Package suitable for TTW-soldering

Empfohlenes Lötpaddesign verwendbar für SmartLED™ und Chipled - Bauform 0603
 IR Reflow Lötten
Recommended Solder Pad useable for SmartLED™ and Chipled - Package 0603
 IR Reflow Soldering



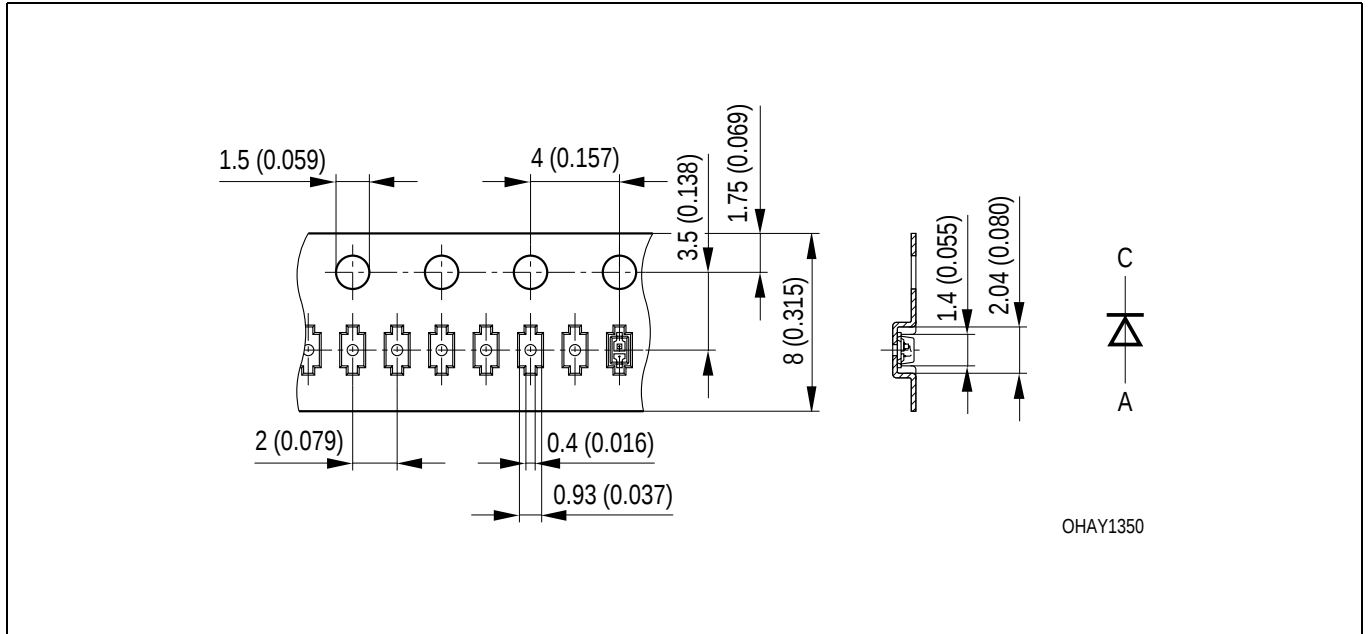
Maße werden wie folgt angegeben: mm (inch) / Dimensions are specified as follows: mm (inch).
 Empfohlene Lötpastendicke: 120 µm / recommended thickness of solder paste: 120 µm
 Gehäuse für Wellenlöten (TTW) geeignet / Package suitable for TTW-soldering

Gurtung / Polarität und Lage

Verpackungseinheit 8 mm Gurt mit 10000/Rolle,
 $\varnothing 180$ mm oder 40000/Rolle, $\varnothing 330$ mm

Method of Taping / Polarity and Orientation

Packing unit 8 mm tape with 10000/reel, $\varnothing 180$ mm
 or 40000/reel, $\varnothing 330$ mm



Maße werden wie folgt angegeben: mm (inch) / Dimensions are specified as follows: mm (inch).

Revision History: 2002-04-05

Previous Version: 2001-03-09

Page	Subjects (major changes since last revision)
2	changed resin from colorless clear to colorless diffused
1	taping changed from 5000 to 10000/reel, ø180 mm and from 20000 to 40000/reel, ø330 mm
4	value (wavelength amber)
12	recommended solder pad
9	Package Outlines
2	wavelength grouping for yellow and orange
3	pad size from 16 mm ² to 5 mm ²

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Attention please!

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Packing

Please use the recycling operators known to you. We can also help you – get in touch with your nearest sales office. By agreement we will take packing material back, if it is sorted. You must bear the costs of transport. For packing material that is returned to us unsorted or which we are not obliged to accept, we shall have to invoice you for any costs incurred.

Components used in life-support devices or systems must be expressly authorized for such purpose! Critical components ¹ may only be used in life-support devices or systems ² with the express written approval of OSRAM OS.

¹ A critical component is a component used in a life-support device or system whose failure can reasonably be expected to cause the failure of that life-support device or system, or to affect its safety or the effectiveness of that device or system.

² Life support devices or systems are intended (a) to be implanted in the human body, or (b) to support and/or maintain and sustain human life. If they fail, it is reasonable to assume that the health of the user may be endangered.